

Solderability Test Report

Report No: VN20230218003-1

Sample Name: PCB

Applicant Department: JBD Ubee

Test Item: Solderability Test

Test Environment: 24.3°C/55.1%RH

Test Completion Date: Feb. 24, 2023

Approved by	Checked by	Prepared by
涂海波	楊光宇	阮氏釵

Notes:

- 1.This report is only applicable to the submitted samples.
- 2.Partial copy this report is prohibitive if not approved by testing center.

1. Problem Description:

In order to verify the soldering quality of PCB from VGT, the solderability test was performed and sample was specified as below.

2. Sample Information:

Sample Name	Mode	P/N	Vendor	D/C
PCB	K18X001T00	308.03524.055	VGT	2215

3. Test Equipment:

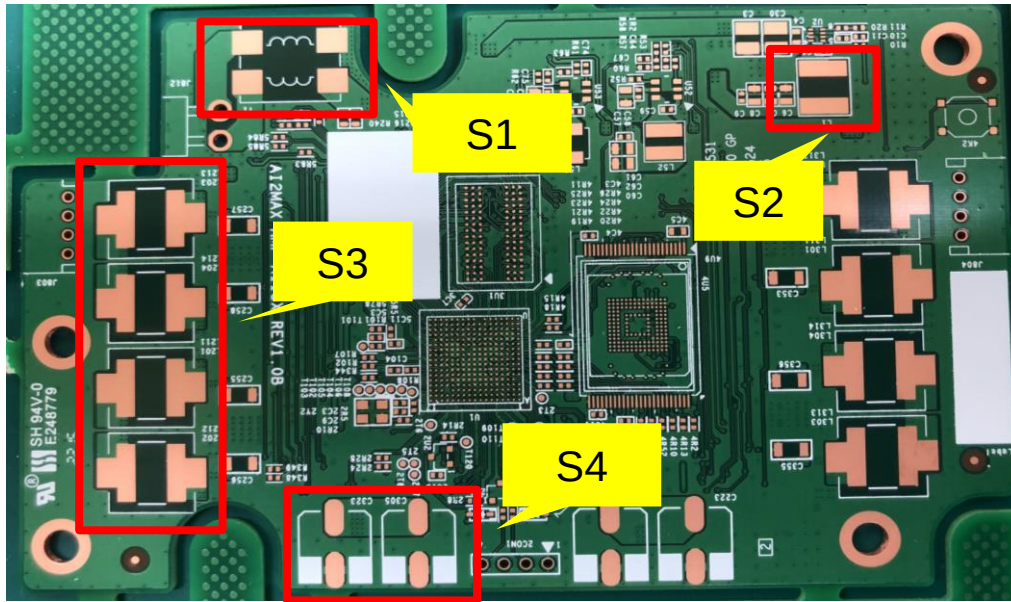
Equipment Name	Model
Wetting Balance	METTRONELEC ST88 NEO

4. Test Condition and Reference Standard

Reference standard:	ELA/IPC/JEDEC J-STD-002E
Solder alloy:	SAC305
Flux type:	ALPHA TF9000-1
Wetting temperature (°C) :	255 °C
Immersion time (s):	10s
Immersion speed:	3mm/s

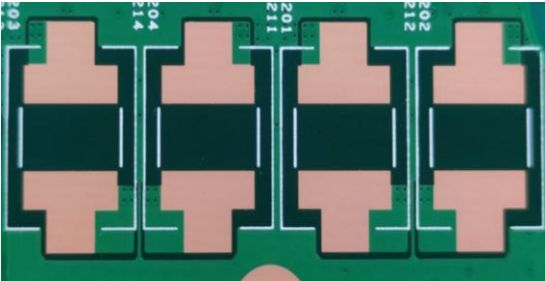
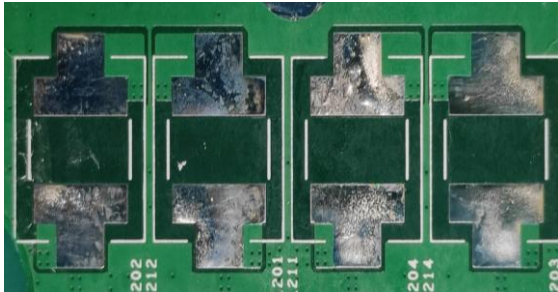
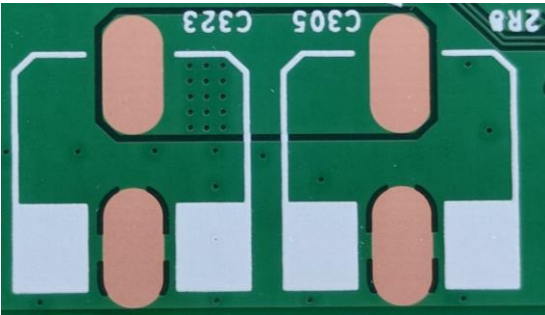
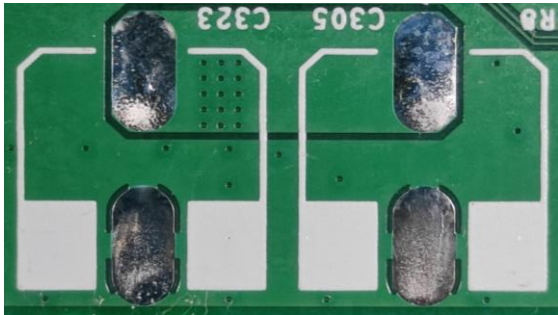
Judge Criterion: The inspected area of each pad must have 95% solder coverage minimum.

5. Appearance of Test Sample:



6. Test Pictures (The representative photos are shown as below):

	Before test	After test	Result
S1			Pass
S2			Pass

	Before test	After test	Result
S3			Pass
S4			Pass